

ABSTRACT

A method for making a package substrate without etching metal layer on side walls of a die-cavity is disclosed. At least a through slot is formed around a defined die-cavity region of a substrate so as to form a die-cavity portion in the die-cavity region. The through slot has side walls without cutting off the die-cavity portion. A metal layer is formed on the side walls inside the through slot. A dry film is attached on the substrate and the die-cavity portion so as to seal the side walls of the through slot. The metal layer on the side walls is reserved during etching. A die-cavity with metalized side walls is formed after removing the die-cavity portion.